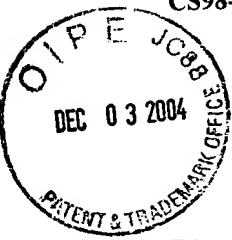


AF/ 2813  
Hw/A

October 22, 2004



TO: Commissioner of Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

FROM: George O. Saile, Reg. No. 19,572  
28 Davis Ave.  
Poughkeepsie, N.Y. 12603

SUBJECT: Serial #: 09/817,473  
File Date: 03/26/2001  
Inventor: YI, XU ET AL.  
Examiner: NGUYEN, THANH T.  
Art Unit: 2813  
Title: GAP FILLING PROCESS IN INTEGRATED  
CIRCUITS USING LOW DIELECTRIC CONSTANT  
MATERIALS

## RESPONSE TO OFFICE ACTION

This is in response to the Office Action dated October 01, 2004. Please consider the following in regards to the above referenced application.

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 1, 2004.

Signature

Date:

12/1/04

Stephen B. Ackerman, Reg. No. 37,761

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Listing of Claims: